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JC97 US PTO

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10055266	01/22/2002	257	138	2811	Q

**APPLICANTS: Choi Ki-yon;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

REPUBLIC OF KOREA 2001-5945 02/07/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 9898-208
Verified and Acknowledged Examiner's initials		
TITLE : Semiconductor package having changed substrate design using special wire bonding		
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due Date Paid

TERMINAL

DISCLAIMER

Assistant Examiner

Primary Examiner

PREPARED FOR ISSUE

CLAIMS ALLOWED

Total Claims

Print Claim for
O.G.

DRAWING

Sheets Drawn

Figs. Drawn

Print Fig.

Application Examiner

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